

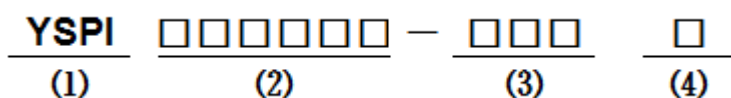
■ Features

- Molding Inductor.
- Low Profile, Low Temp.
- Large Current (Over 15A).
- Customize For Different Need.
- Operating temperature: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$.

■ Applications

- General Electronic.
- Video Device, TV, TFT.
- Power Module for PC.
- NB/Lap Top Computer.
- Server, VGA Card/Module.

■ Product Identification



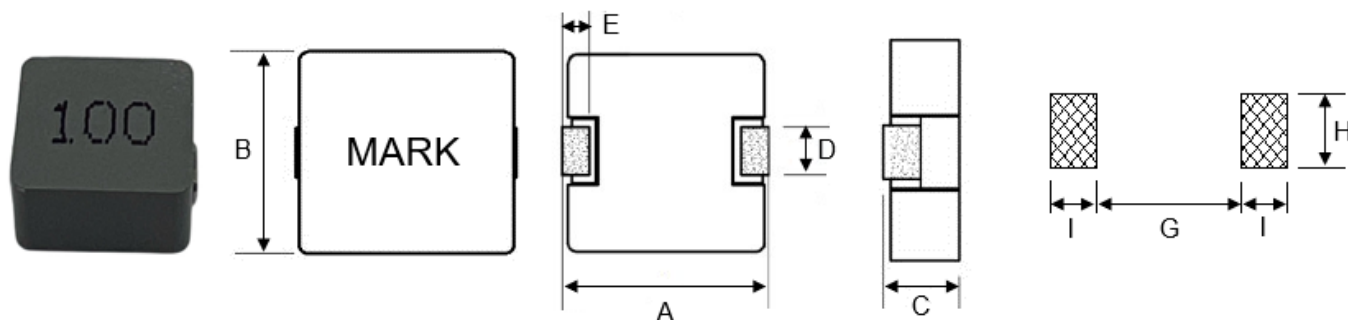
(1) : Type

(2) : Dimensions

(3) : Inductance value

(4) : Inductance Tolerance : N=±30%, M=±20%

■ Shapes and Dimensions (Unit: mm)



TYPE	A	B	C Max.	D	E	G Ref.	H Ref.	I Ref.
YSPI1060TP	10.5±1.0	10.3±0.3	6.0	3.0±0.3	2.0±0.5	6.0	4.0	3.5

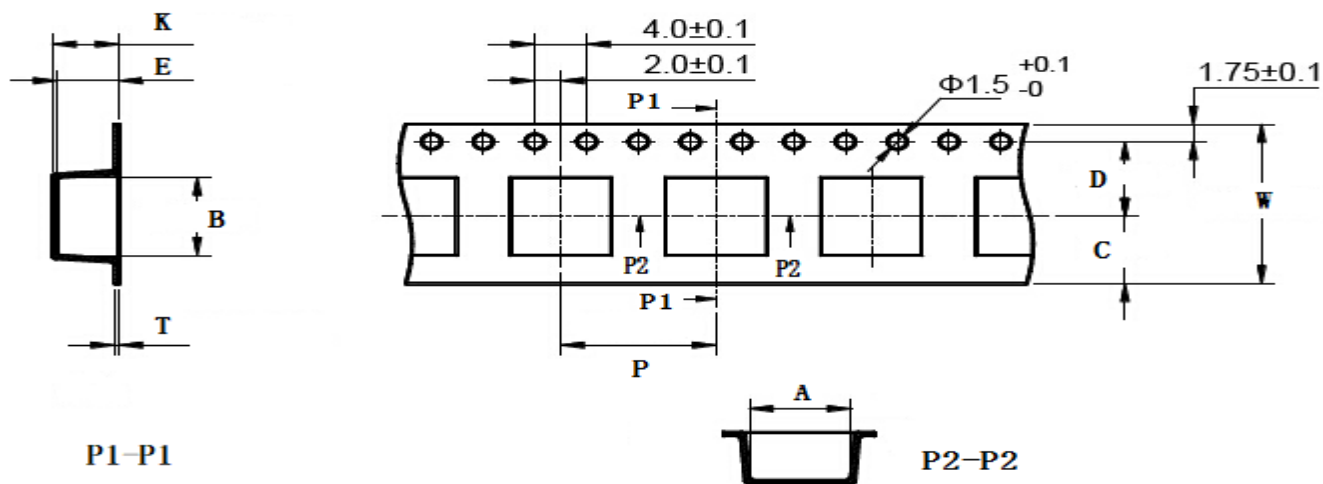
Electrical Characteristic

Part Number	Inductance (uH) @100KHz	DC Resistance (mΩ)		Heat Rating Current (A)	Saturation Current (A)
		Typ.	Max.		
YSPI1060TP-100M	10	17.3	20.0	10.0	18.0

- ※ The saturation current value is the DC current value having inductance decrease down to 30%. (at 20℃)
- ※ The temperature rise current value is the DC current value having temperature increase up to 40℃. (at 20℃)
- ※ The rated current is the DC current value that satisfies both of current value saturation current value and temperature rise current value.

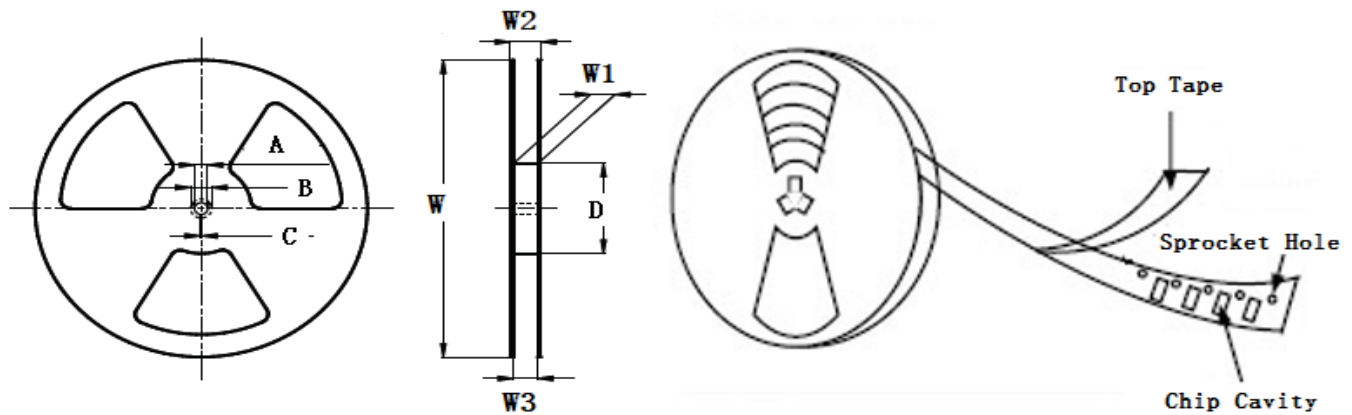
※

Taping Dimensions(Unit:mm)



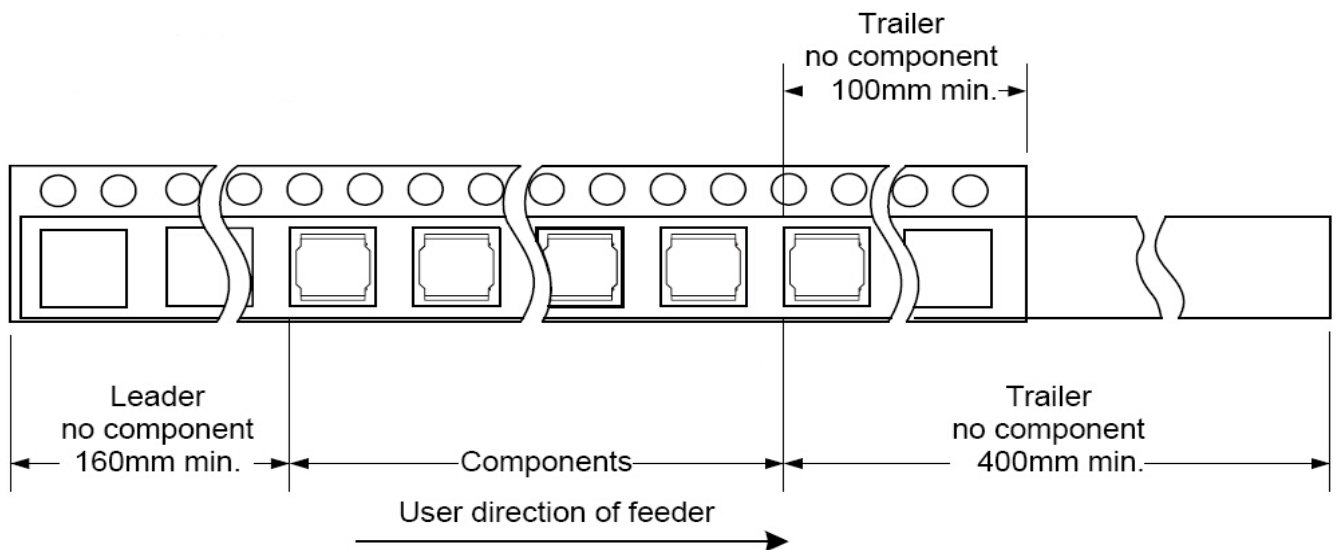
TYPE	W	A	B	C	D	E	P	K Ref	T	MPQ
YSPI1060TP	24±0.3	10.6±0.1	11.45±0.1	10.75	11.5±0.1	5.5±0.1	16±0.1	5.1	0.40±0.05	500

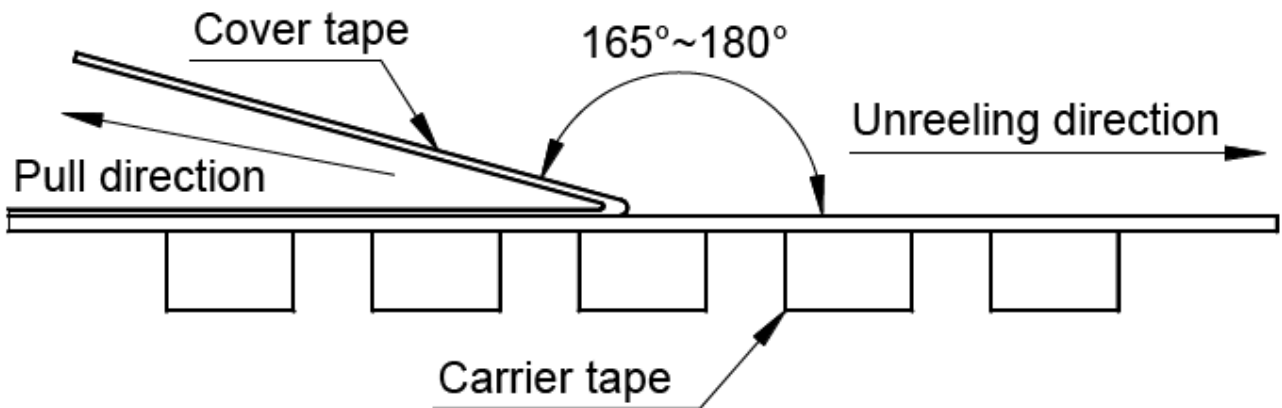
■ Reel Dimensions(Unit:mm)



TYPE	W	W1	W2	W3	A	B	C	D
YSPI1060TP	330±2.0	24.4±1.5	30.4MAX	23.9 Min	13.0±0.50	21.0±0.80	2.0±0.50	100 Min

■ Direction of rolling



■ Cover tape peel off condition

Cover tape peel force shall be 0.1N to 1.3N.

Reference peel speed $300 \pm 10 \text{ mm/min}$.